# S U M M A R Y

The invention relates to an apparatus for the cleaning of thin wafers (6), wherein the wafers (6) are fixed with one side to a carrier device (2), and wherein an interspace (7) is formed between two adjacent substrates, wherein the apparatus substantially consists of a shower device (15) by which fluid is injected into the respective interspaces (7), and a basin (14) that can be filled with fluid and that is dimensioned such that it houses the carrier device (2).

According to the invention, optionally either the shower device (15) can be moved in relation to the immobile carrier device (2), or the carrier device (2) can be moved in relation to the immobile shower device (15), or both the carrier device (2) as well as the shower device (15) can be moved in relation to each other.

The method stands out by the fact that in a preferred cleaning process, a shower with warm fluid takes place at first with the carrier device (2) being moved within the basin, followed by an ultrasonic cleaning in cold fluid and another shower with warm fluid.

(Fig. 5 B)